

TECHNICAL DATASHEET

VITRALIT® UD 8050 LV



PRODUCT DESCRIPTION

Modified acrylate | 1 part | solvent-free | UV / Visible light curing | secondary humidity cure

- ▶ Protective encapsulation of electronic components on PCB
- ▶ Consumer electronics
- ▶ Tack-free surface
- ▶ Compatible with flux
- ▶ Short-term stable up to 150 ° C
- ▶ Fast curing

CURING PROPERTIES

UV-A	LED 365nm	LED 405nm	Secondary humidity cure
✓	✓	✓	✓

✓ suitable – not suitable

In cases where UV curing is applicable, humidity may only be used as a secondary process for shadowed areas.

Light-curing (Hoenle Discharge Lamp)

Intensity [mW/cm²]*	Layer thickness [mm]	Time [s]
60	0.1	5

*measured by Hoenle UV-Meter 3.0 / UV-A F0

LED-curing (Hoenle LED Spot 100, 365nm)

Intensity [mW/cm²]**	Layer thickness [mm]	Time [s]
300	0.1	2

LED-curing (Hoenle LED Spot 100, 405nm)

Intensity [mW/cm²]**	Layer thickness [mm]	Time [s]
500	0.1	2

**measured by Hoenle UV-Meter 3.0 / LED F2

To obtain full cure at least one substrate must be transparent to the recommended wavelength. The curing speed depends on the wavelength spectrum of the light source, the intensity of light, the distance to the light source, the component geometry and the amount of adhesive.

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Resin	Isocyanate acrylate
Appearance	Transparent, slightly yellow
Uncured Material	
Viscosity [mPas] (Kinexus Rheometer, 25 °C, 5s ⁻¹) <i>Test instruction P064</i>	200 – 400
Density [g/cm ³] <i>Test instruction P004</i>	1.0 – 1.2
Refractive index [nD20] <i>Test instruction P023</i>	1.49 – 1.50
Working life [days] <i>@ room temperature</i>	3
Cured Material	
Typical operating temperature [°C]	-40 – 130
Linear shrinkage [%] <i>Test instruction P031</i>	<2
Water absorption [wt%] <i>Test instruction P016</i>	<3

	Shore hardness D	Bonding strength*
12h after UV-cure**	40 – 60	20% of final strength
+5 days humidity cure***	60 – 80	85% of final strength
+9 days humidity cure ***	70 – 90	50 – 65N

***Ceramic resistance die 1206 (3.2mm x 1.6mm). The ceramic die which has no light transmission is bonded to PCB with adhesive, UV only cures the adhesive on edge and fixes the die. The adhesive under the die is then cured with humidity over time.**

**** UV cure: UVA lamp, Fe-doped, 60 mW/cm², 30 s.**

***** Humidity cure: 25°C, 50% RH.**

Glass transition temperature – DSC [°C] <i>Test instruction P009</i>	40 – 60
Coefficient of thermal expansion [ppm/K] below T _g <i>Test instruction P017</i>	30 – 70
Coefficient of thermal expansion [ppm/K] above T _g <i>Test instruction P017</i>	180 – 240
Storage modulus – DMA [MPa] <i>UV-A Fe-doped hand lamp, 60mW/cm², 30s + RT, 14d, 65%RH</i>	150 – 180
Tensile strength [MPa] <i>UV-A Fe-doped hand lamp, 60mW/cm², 30s + RT, 14d, 65%RH</i>	30 – 40
Elongation at break [%] <i>UV-A Fe-doped hand lamp, 60mW/cm², 30s + RT, 14d, 65%RH</i>	4 – 6

TRANSPORT/STORAGE/SHELF LIFE

Package type	Transport	Storage	Shelf life*
Syringe/Cartridge	0°C – 10°C	0°C – 10°C	At delivery min. 3 months max. 6 months
Other packages			

****Store in original, unopened containers!***

INSTRUCTIONS FOR USE

Surface preparation

The surfaces to be bonded should be free of dust, oil, grease, mold release, or other contaminants in order to obtain an optimal and reproducible bond. For cleaning we recommend the cleaner IP® from Hoenle, or a solution of Isopropyl Alcohol at 90% or higher concentration. Substrates with low surface energy (e.g. polyethylene, polypropylene) must be pretreated in order to achieve sufficient adhesion.

Application

Our products are supplied ready to use. Depending on the packaging, our adhesives may be dispensed by hand directly from the package, or they can be applied using dispensing systems and automation that is compatible with light-curable adhesive chemistry. Vitralit® adhesives can begin to cure slowly in daylight and with longer term exposure under indoor lighting. We therefore recommend that adhesive exposure to ambient light must be kept to a minimum. Fluid lines and dispense tips must be 100% light blocking. For assistance with dispensing options, please contact our Application Engineering department. Adhesive and substrate should not be cold for proper bonding. They must be allowed to warm to room temperature prior to processing. After dispensing the adhesive, bonding of the parts should be done promptly. It is recommended that curing stations be equipped with air exhaust systems to evacuate vapors and heat generated during the curing process. After curing, the adhesive must be allowed to cool to ambient temperature before testing the product's performance. For safety information refer to our Material Safety Data Sheet (MSDS).

Storage

This is light sensitive material. Containers must remain covered when not in use. Minimize exposure of uncured material to daylight, artificial light, and UV light during storage and handling. Store uncured product in its original, closed container in a dry location. Any material removed from the original container must not be returned to the container as it could be contaminated. Hoenle cannot assume responsibility for products that were improperly stored, contaminated, or repackaged into other containers.

Handling and Clean-up

For safe handling information, consult this product's Material Safety Data Sheet (MSDS) prior to use. Uncured material may be wiped away from surfaces with organic solvents. Do not use solvents to remove material from eyes or skin!

DISCLAIMER

The product is free of heavy metals, PFOS and Phthalates and is conform to the current EU-Directive RoHS.

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